

FQA11N90 / FQA11N90_F109

N-Channel QFET® MOSFET

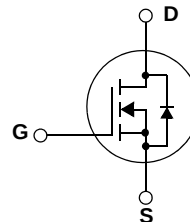
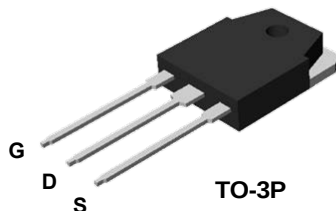
900 V, 11.4 A, 960 mΩ

Features

- 11.4 A, 900 V, $R_{DS(on)} = 960\text{ m}\Omega$ (Max.) @ $V_{GS} = 10\text{ V}$, $I_D = 5.7\text{ A}$
- Low Gate Charge (Typ. 72 nC)
- Low C_{rss} (Typ. 30 pF)
- 100% Avalanche Tested
- RoHS Compliant

Description

This N-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power factor correction (PFC), and electronic lamp ballasts.



Absolute Maximum Ratings

Symbol	Parameter	FQA11N90	Unit
V_{DSS}	Drain-Source Voltage	900	V
I_D	Drain Current - Continuous ($T_C = 25^\circ\text{C}$)	11.4	A
	- Continuous ($T_C = 100^\circ\text{C}$)	7.2	A
I_{DM}	Drain Current - Pulsed (Note 1)	45.6	A
V_{GSS}	Gate-Source Voltage	± 30	V
E_{AS}	Single Pulsed Avalanche Energy (Note 2)	1000	mJ
I_{AR}	Avalanche Current (Note 1)	11.4	A
E_{AR}	Repetitive Avalanche Energy (Note 1)	30	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	4.0	V/ns
P_D	Power Dissipation ($T_C = 25^\circ\text{C}$)	300	W
	- Derate above 25°C	2.38	W/ $^\circ\text{C}$
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
T_L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	FQA11N90	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	0.42	$^\circ\text{C/W}$
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink, Typ.	0.24	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	40	$^\circ\text{C/W}$

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FQA11N90	FQA11N90	TO-3P	--	--	30
FQA11N90	FQA11N90_F109	TO-3PN	--	--	30

Electrical Characteristics T_C = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
Off Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0 V, I _D = 250 μA	900	--	--	V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C	--	1.0	--	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 900 V, V _{GS} = 0 V	--	--	10	μA
		V _{DS} = 720 V, T _C = 125°C	--	--	100	μA
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V	--	--	100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30 V, V _{DS} = 0 V	--	--	-100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250 μA	3.0	--	5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 5.7 A	--	0.75	0.96	Ω
g _{FS}	Forward Transconductance	V _{DS} = 50 V, I _D = 5.7 A (Note 4)	--	12	--	S
Dynamic Characteristics						
C _{iSS}	Input Capacitance	V _{DS} = 25 V, V _{GS} = 0 V, f = 1.0 MHz	--	2700	3500	pF
C _{oSS}	Output Capacitance		--	260	340	pF
C _{rSS}	Reverse Transfer Capacitance		--	30	40	pF
Switching Characteristics						
t _{d(on)}	Turn-On Delay Time	V _{DD} = 450 V, I _D = 11.4A, R _G = 25 Ω (Note 4, 5)	--	65	140	ns
t _r	Turn-On Rise Time		--	135	280	ns
t _{d(off)}	Turn-Off Delay Time		--	165	340	ns
t _f	Turn-Off Fall Time		--	90	190	ns
Q _g	Total Gate Charge	V _{DS} = 720 V, I _D = 11.4A, V _{GS} = 10 V (Note 4, 5)	--	72	94	nC
Q _{gs}	Gate-Source Charge		--	16	--	nC
Q _{gd}	Gate-Drain Charge		--	35	--	nC
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain-Source Diode Forward Current		--	--	11.4	A
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current		--	--	45.6	A
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S =11.4 A	--	--	1.4	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _S = 11.4 A, dI _F / dt = 100 A/μs (Note 4)	--	850	--	ns
Q _{rr}	Reverse Recovery Charge		--	11.2	--	μC

NOTES:

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2. L = 15mH, I_{AS} = 11.4A, V_{DD} = 50V, R_G = 25 Ω, Starting T_J = 25°C
3. I_{SD} ≤ 11.4A, di/dt ≤ 200A/μs, V_{DD} ≤ BV_{DSS}, Starting T_J = 25°C
4. Pulse Test : Pulse width ≤ 300μs, Duty cycle ≤ 2%
5. Essentially independent of operating temperature

Typical Performance Characteristics

Figure 1. On-Region Characteristics

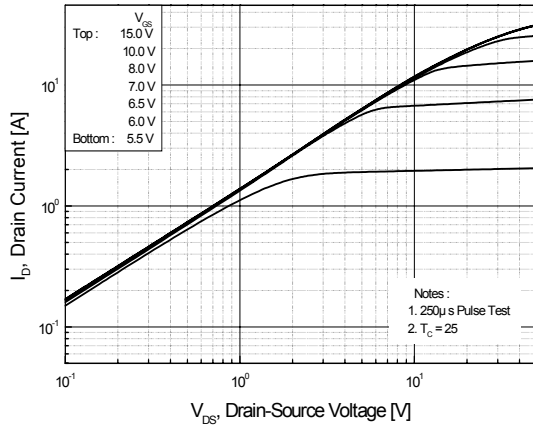


Figure 2. Transfer Characteristics

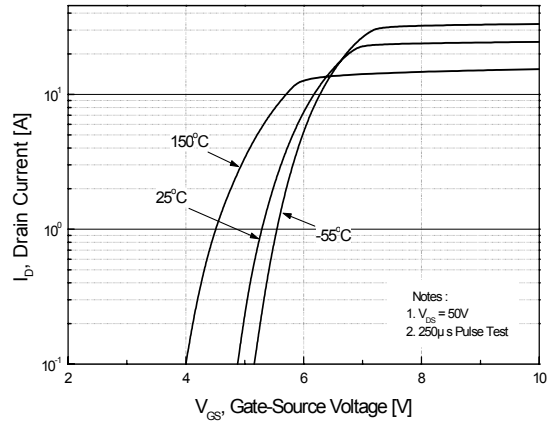


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

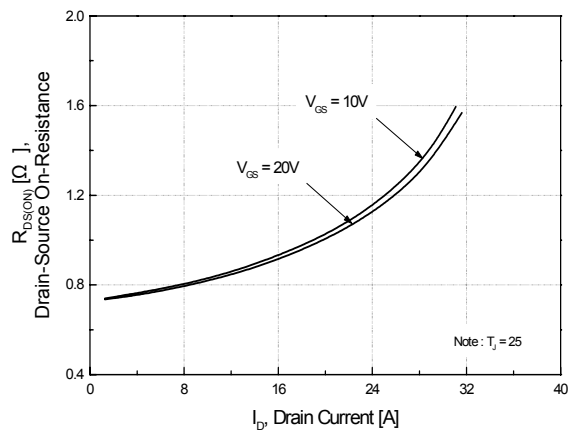


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

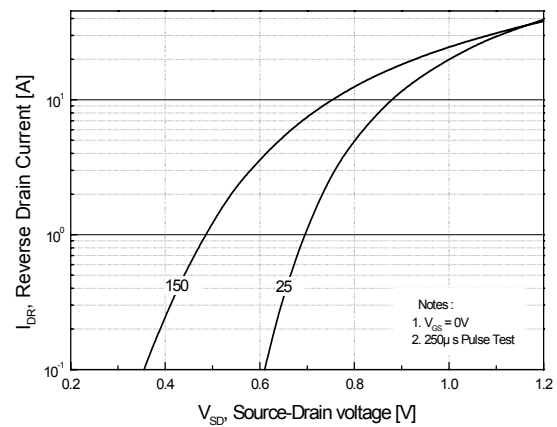


Figure 5. Capacitance Characteristics

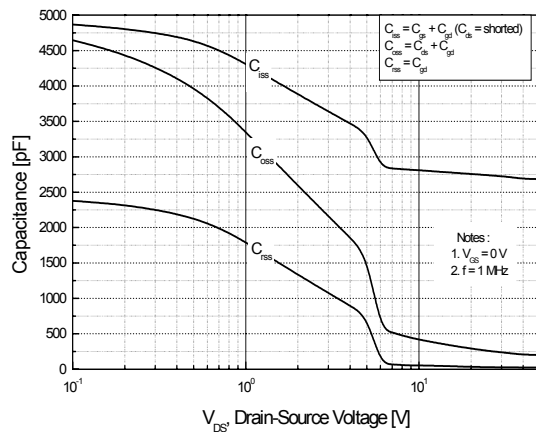
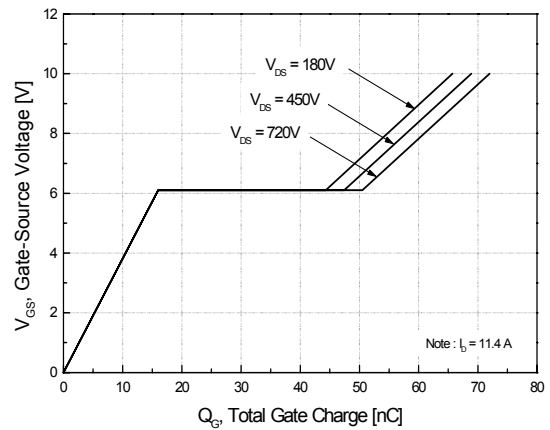


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

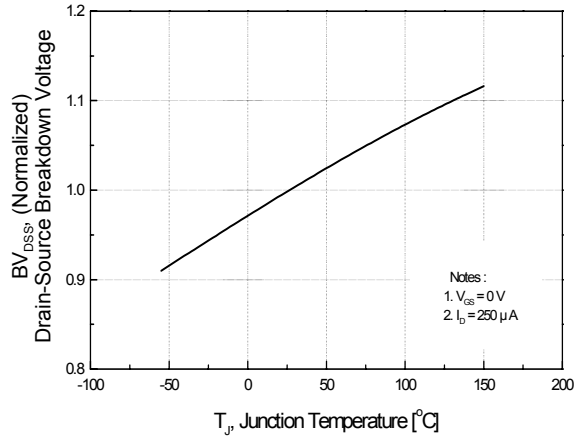


Figure 8. On-Resistance Variation vs. Temperature

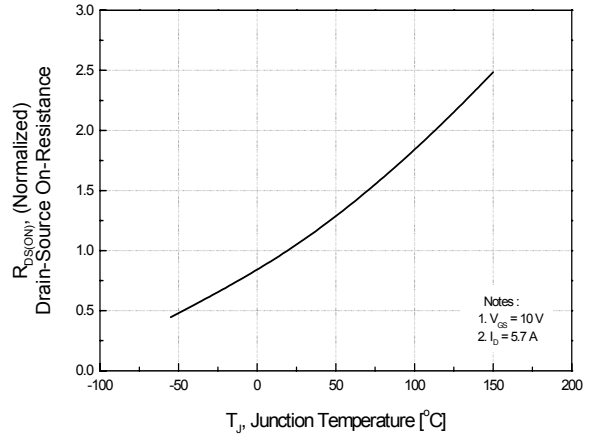


Figure 9. Maximum Safe Operating Area

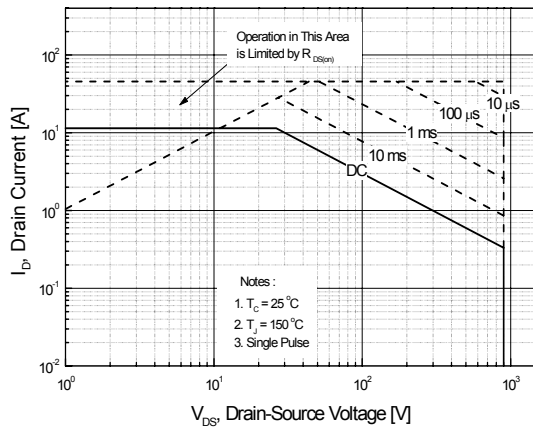


Figure 10. Maximum Drain Current vs. Case Temperature

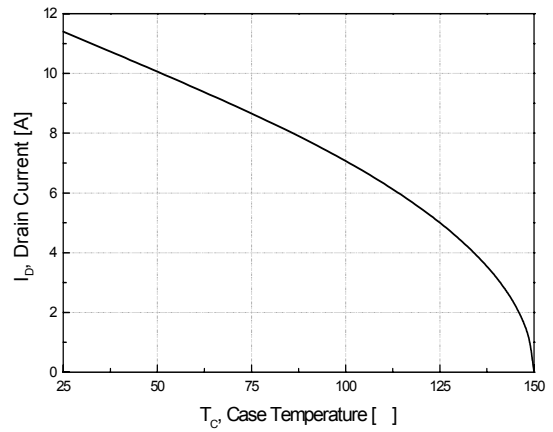
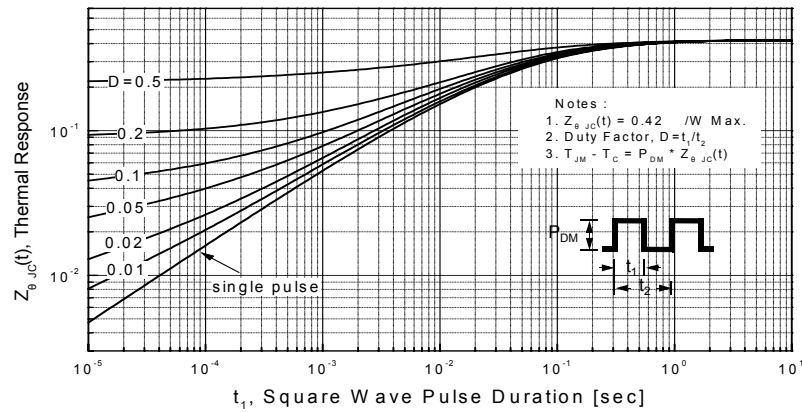
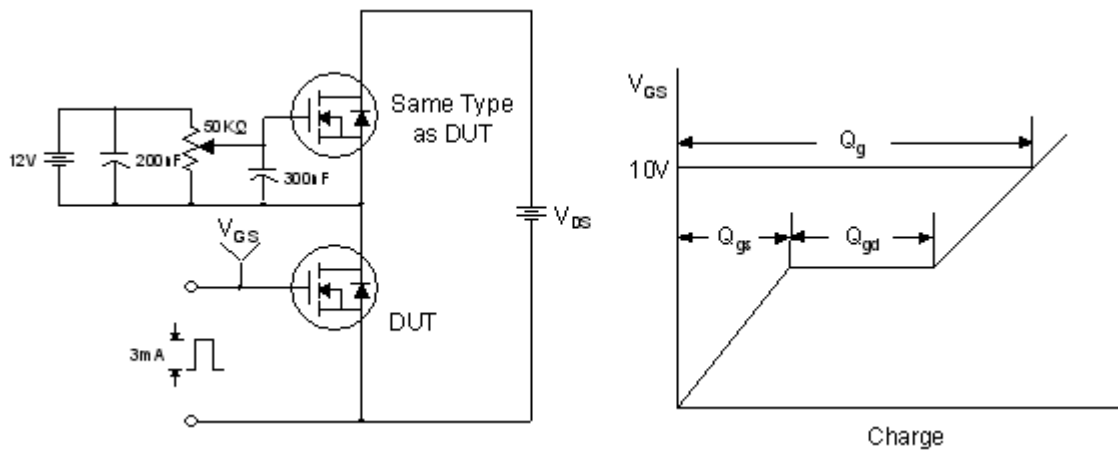


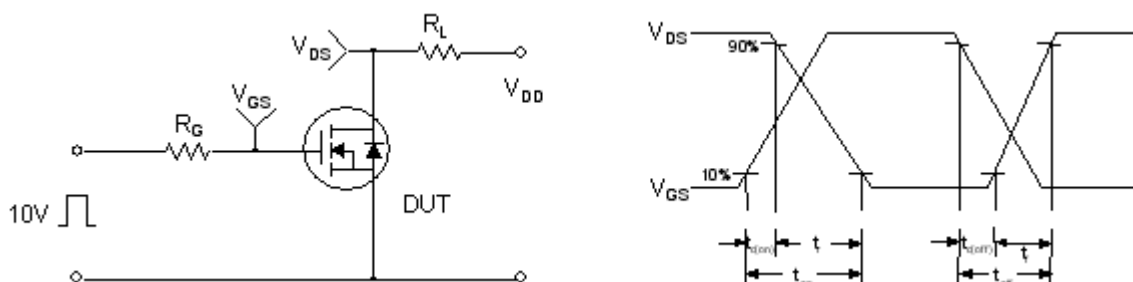
Figure 11. Transient Thermal Response Curve



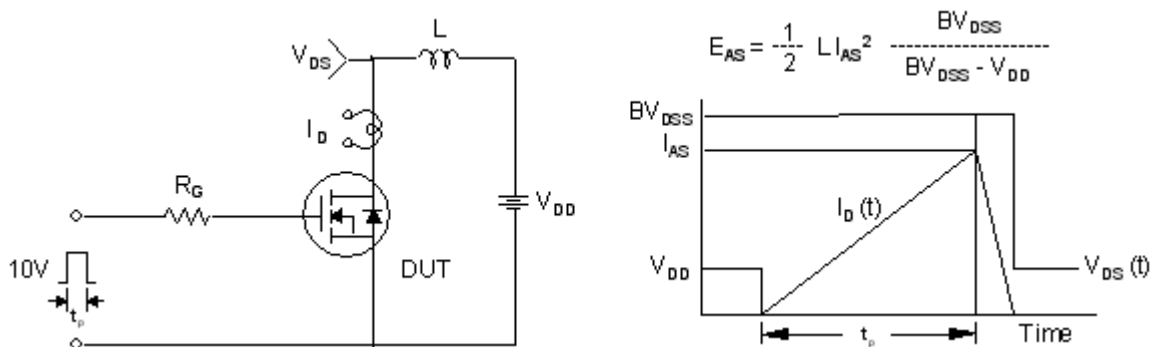
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms

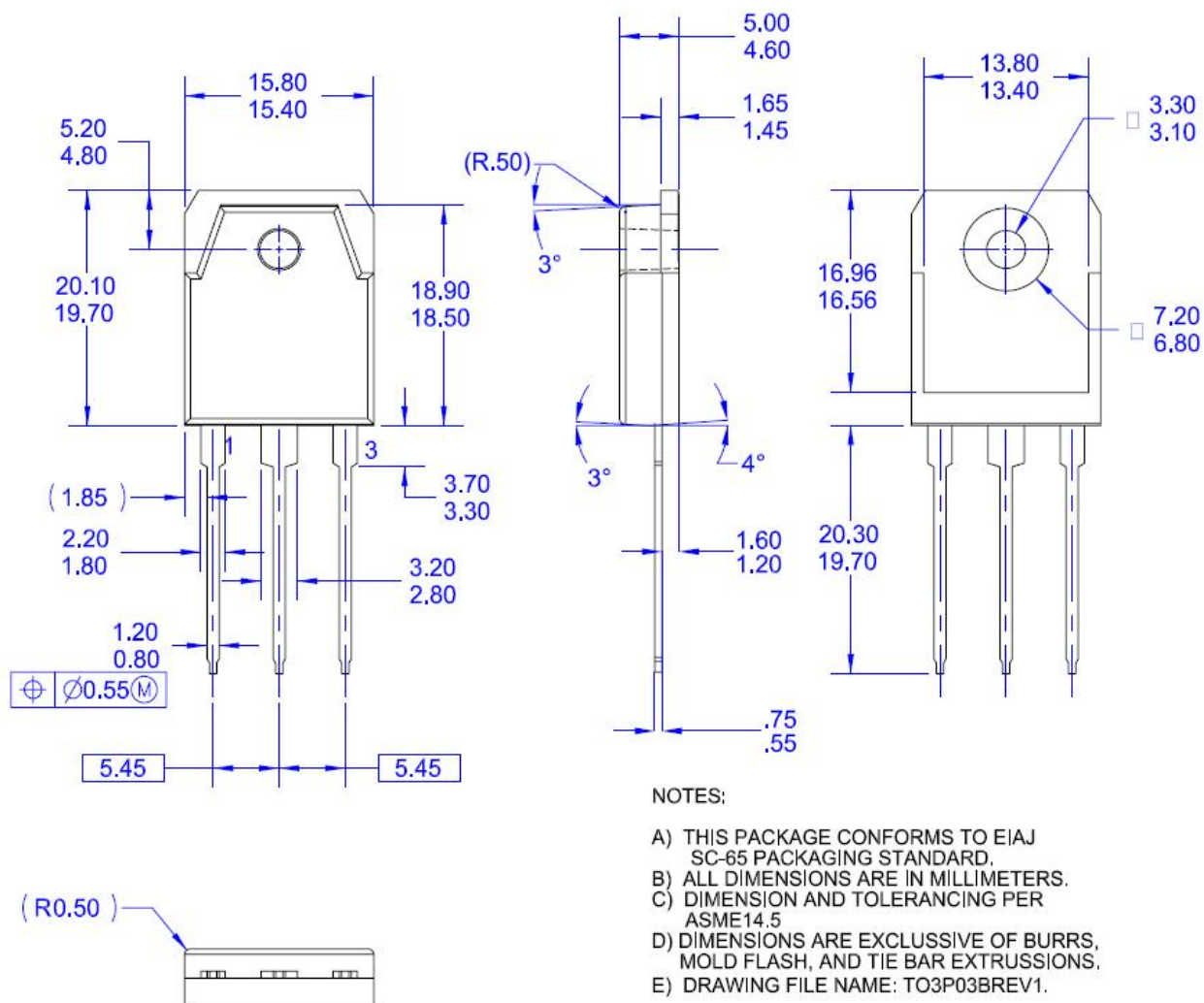


Unclamped Inductive Switching Test Circuit & Waveforms



Mechanical Dimensions

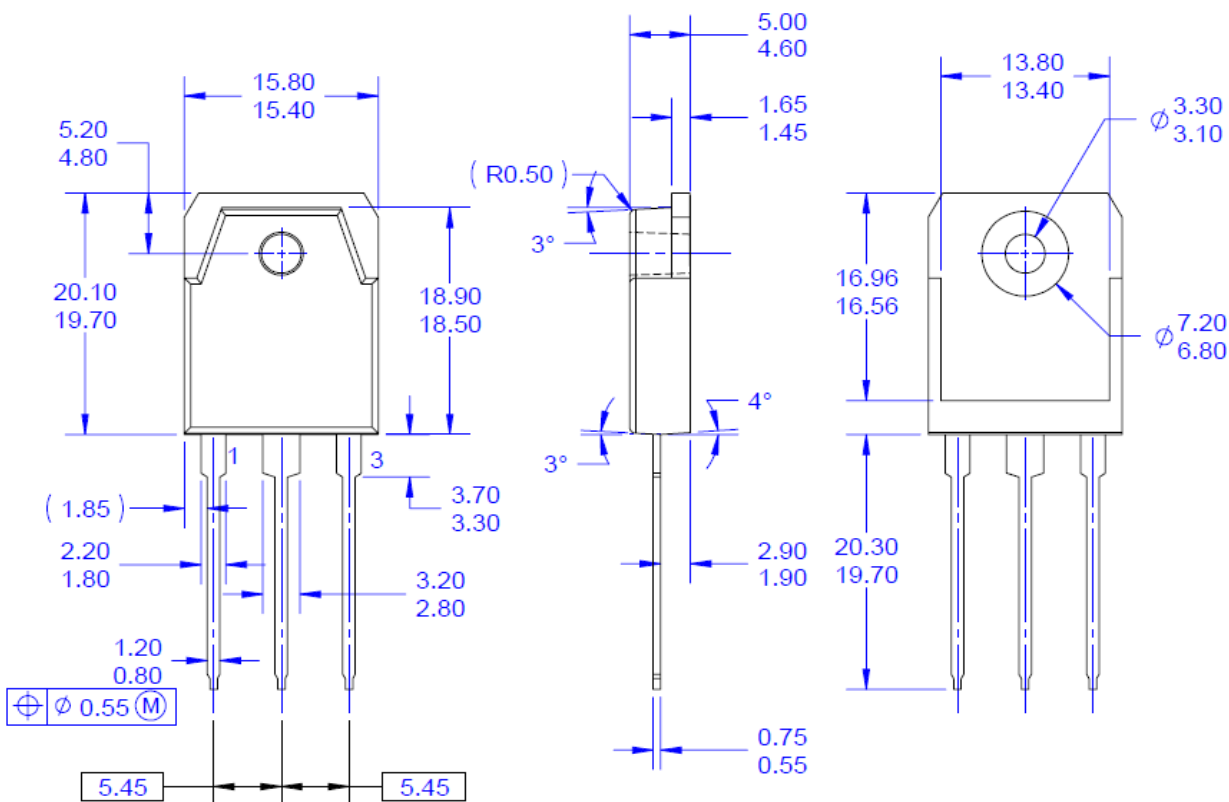
TO-3P



Dimensions in Millimeters

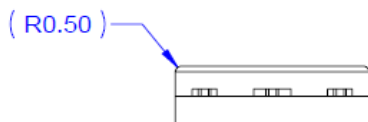
Mechanical Dimensions

TO-3PN



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